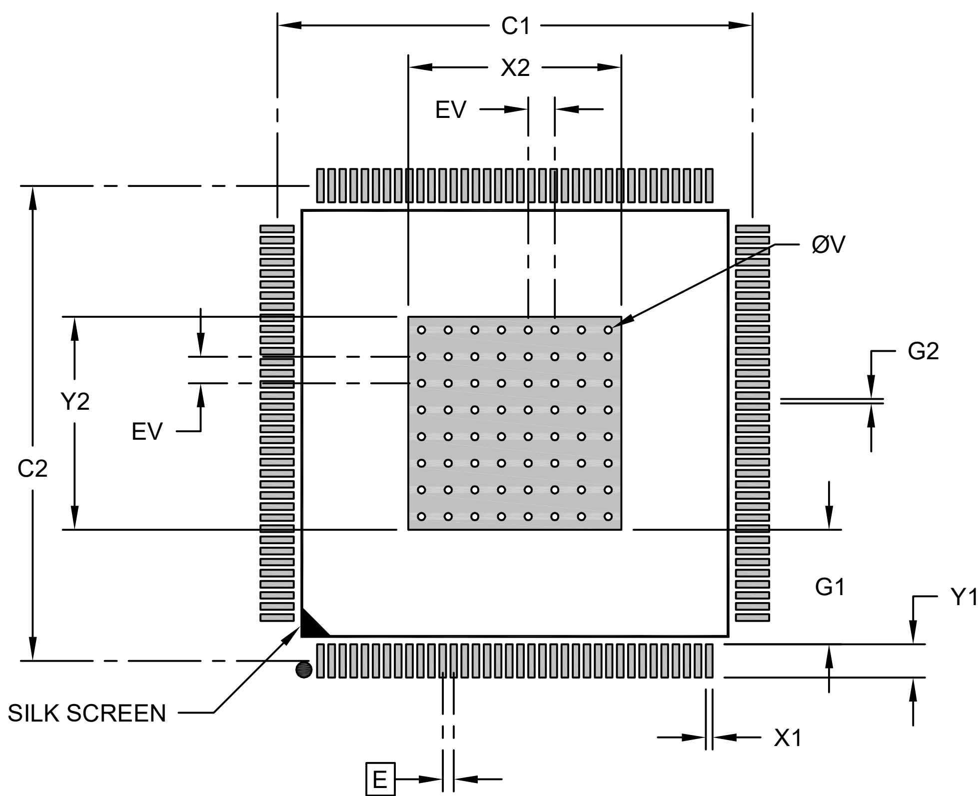
144-Lead Plastic Thin Quad Flat Pack (8YX) - 20x20x1.0 mm Body [TQFP] With 9.5 mm Exposed Pad

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Center Pad Width	X2			9.60
Center Pad Length	Y2			9.60
Contact Pad Spacing	C1		21.40	
Contact Pad Spacing	C2		21.40	
Contact Pad Width (Xnn)	X1			0.30
Contact Pad Length (Xnn)	Y1			1.50
Contact Pad to Center Pad (Xnn)	G1	5.15		
Contact Pad to Contact Pad (Xnn)	G2	0.20		
Thermal Via Diameter	V		0.33	
Thermal Via Pitch	EV		1.20	

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
2. For best soldering results, thermal vias, if used, should be filled or tented to avoid solder loss during reflow process